This Sheet Has Been Replaced



ABSTRACT OF THE DISCLOSURE

Partial wafer processing is achieved by down loading the wafer map of the whole wafer from a host (12) and if the partial wafer contains the reference die (14) move table to a locator die (15) and upload locator die coordinates to wafer map data host (16) and remove other partial wafer die coordinates from the map (17). If the partial wafer does not have the reference die and is not the last partial wafer, position wafer table to auxiliary reference die (18), validate the auxiliary reference die position (19) and compute auxiliary reference die coordinates from locator die coordinates (20) and move wafer table to locator die (22) and upload locator die coordinates to wafer map data host (23) and then using auxiliary reference die and locator die coordinates as information remove other partial wafer die coordinates from the map (24). If the partial wafer does not have the reference die and is the last partial wafer, position wafer table to auxiliary reference die (18), validate the auxiliary reference die position (19) and compute auxiliary reference die coordinates from locator die coordinates (20) and then using auxiliary reference die coordinates as information remove other partial wafer die coordinates from the map (25).

Received Time 5. Feb. 7:08 Print Time 5. Feb. 8:15